

# Product/process change notification

**PCN222201**

Please find attached our Infineon Technologies AG PCN:

## Introduction of an additional wafer bumping production site at Powertech Technology Inc. Hsinchu, Taiwan for select plated bump Flip Chip FBGA IOT products

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **20 Jul 2022**
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates: **“Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”**

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



On 16 April 2020, Infineon acquired Cypress.  
We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.  
For further details, please visit our website:  
<https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/>

► **Products affected:** Please refer to attached affected product list [4]

► **Detailed change information:**

**Subject:** Introduction of an additional wafer bumping production site at Powertech Technology Inc., Hsinchu, Taiwan for select plated bump Flip Chip FBGA IOT products.

**Reason:** Expansion of bumping production to assure continuity of supply and enable flexible manufacturing.

<b>Description:</b>	<u>Old</u>	<u>New</u>
	<ul style="list-style-type: none"> <li>■ Taiwan Semiconductor Manufacturing Company, Ltd., Tainan, Taiwan Or</li> <li>■ Advanced Semiconductor Engineering Inc. Kaohsiung, Taiwan</li> </ul>	<ul style="list-style-type: none"> <li>■ Taiwan Semiconductor Manufacturing Company, Ltd., Tainan, Taiwan Or</li> <li>■ Advanced Semiconductor Engineering Inc. Kaohsiung, Taiwan Or</li> <li>■ Powertech Technology Inc., Hsinchu, Taiwan</li> </ul>

► **Product identification:** Traceability of product to assembly site through the lot number marked on the package.

► **Impact of change:** Based on the qualification performed, Infineon does not see any negative impact on quality, function and reliability. No change in fit and form.

► **Attachments:** Affected product list [4]  
Supporting documents

► <b>Time schedule:</b>	
■ Final qualification report:	available
■ First samples available:	on request
■ Intended start of delivery:	2022-09-08

If you have any questions, please do not hesitate to contact your local sales office.

**[Product Change Notification] N° [PCN222201]**

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Hsinchu, Taiwan for select plated bump Flip Chip FBGA IOT products



Item	Marketing Part Number	Family	Sample Order Part Number	Sample Availability
1	CYW43012TC0KFFBH	WIFI	CYW43012TC0KFFBHX	available
2	CYW43242KFFB4G	WIFI	CYW43242KFFBZ4G	available
3	CYW43243KFFBG	WIFI	CYW43243KFFBZG	available
4	CG9233AM	WIFI	CG9233XM	subject to leadtime